

SERIES LCF AND LCH

- FEATURES
- STANDARD 8 AND 14 DIP PACKAGE
- TOLERANCE AND STABILITY TO ±25PPM
- EXCELLENT CLOCK FOR 16 AND 32 BIT PROCESSORS
- LOW COST
- AVAILABLE IN 3.3 VOLT

● SPECIFICATIONS

SERIES		LCF	LCH
PACKAGE		14PIN DIP	8PIN DIP
FREQUENCY RANGE		500.00 KHz TO 125.00 MHz	500.00 KHz TO 125.00 MHz
FREQUENCY STABILITY†		LCF100:±100 PPM	LCH100:±100 PPM
		LCF100:±50 PPM	LCH100:±50 PPM
		LCF100:±25 PPM	LCH100:±25 PPM
OPERATING TEMPERATURE		0 TO 70 STANDARD -40 TO 85 EXTENDED	0 TO 70 STANDARD -40 TO 85 EXTENDED
STORAGE TEMPERATURE		-55 TO + 125	-55 TO + 125
INPUT	VOLTAGE ††	+5C VDC ± 0.5VCD	+5C VDC ± 0.5VCD
	CURRENT(MAX)	500KHz TO 19.999MHz:20mA	500KHz TO 19.999MHz:20mA
		20KHz TO 34.999MHz:30mA	20KHz TO 34.999MHz:30mA
		35KHz TO 69.999MHz:40mA	35KHz TO 69.999MHz:40mA
	70KHz TO 125MHz:60mA	70KHz TO 125MHz:60mA	
CUTPUT	SYMMETRY	40 TO 60 % NORMAL 45 TO 55 % TIGHT	40 TO 60 % NORMAL 45 TO 55 % TIGHT
		RISE AND FALL TIME(0.5-4.5VDL)	UNDER 24 MHz:±10 ns MAX
	24 MHz TO 70MHz:±6 ns MAX		24 MHz TO 70MHz:±6 ns MAX
	70 MHz TO 125MHz:±3 ns MAX		70 MHz TO 125MHz:±3 ns MAX
	LOGIC"0"LEVEL	+0.5 V MAX.(10 % VDD)	+0.5 V MAX.(10 % VDD)
	LOGIC"1"LEVEL	+4.5 V MIX.(90 % VDD)	+4.5 V MIN.(90 % VDD)
	LOAD†††	15 OF OR 10 LS TTL STANDARD	15 OF OR 10 LS TTL STANDARD

†FREQUENCY STABILITY INCLUSIVE OF ROOM TOLERANCE,FREQUENCY STABILITY OVER TEMPERATURES.

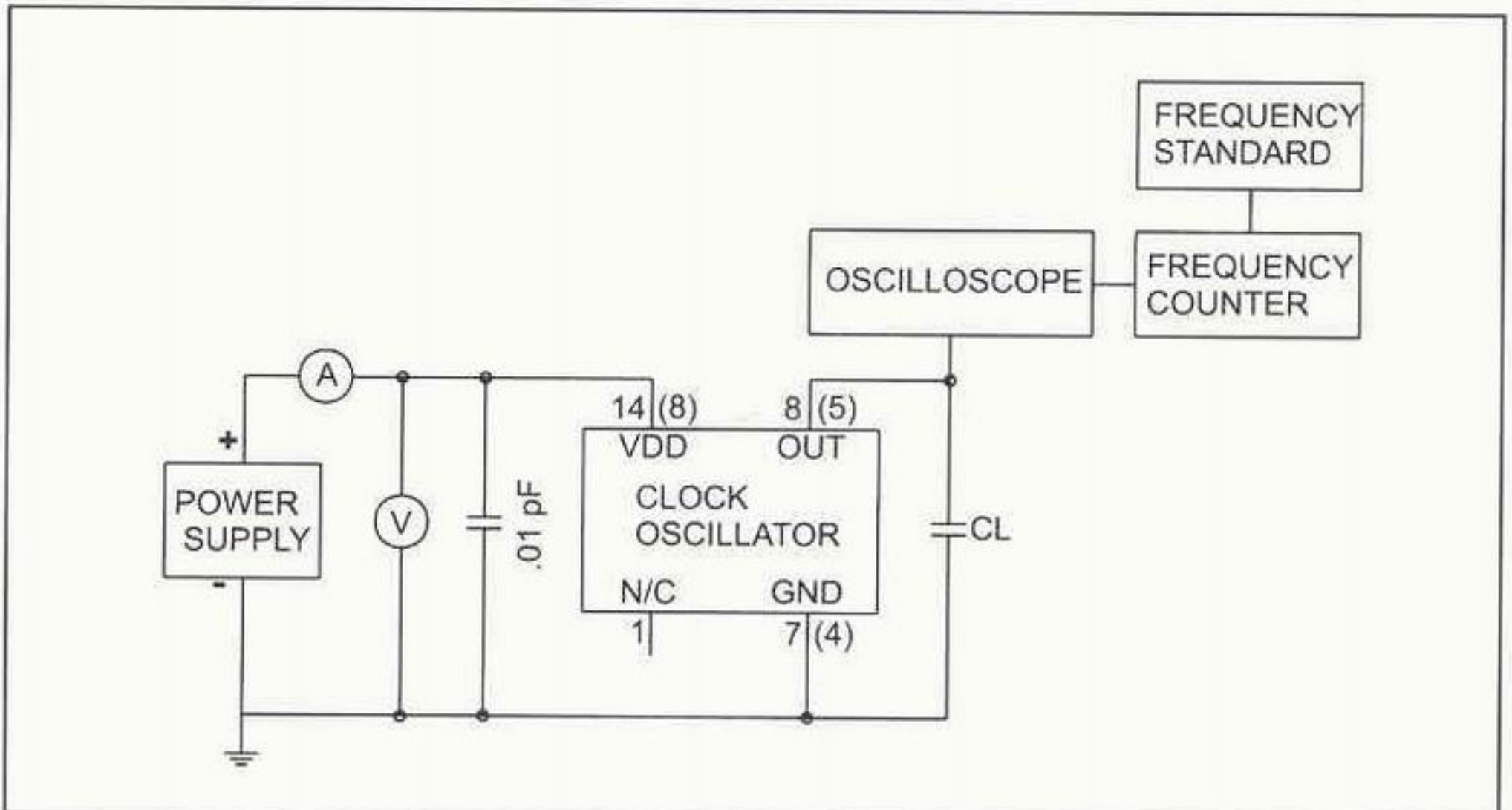
10% POWER SUPPLY VARIATION,AGING,SHOCK,AND VIBRATION

†† +3.3 VOLT VERSION IS AVAILABLE.CONSULT RALTRON FOR SPECIFICATIONS

††† OUTPUT LOADS ALSO AVAILABLE AT 15 OF ,30PF AND 50pF CONAULT RALTRON FOR

SPECIFICATIONS

●TEST CIRCUIT



● PART NUMBERING SYSTEM

SERIES		FREQUENCY STABILITY		FREQUENCY	EXTENDED TEMPERATURE	SYMMETRY		OPTIONS	
LCF	(14 PIN DIP)	100	±100PPM	IN MHz	EXT	T	TIGHT SYMMETRY	TR	TAPE AND REEL
		50	±50PPM					GW	GULL WING
LCH	(8 PIN DIP)	25	±25PPM					3.3V	+3.3V

EXAMPLE:LCF-100-10.000-EXT-T,LCH50-32.000-EXT-T-TR

● ENVIRONMENTAL AND TECHNICAL CONDITIONS

ENVIRONMENTAL	
TEMPERATURE CYCLE	MIL-STD 883,METHOD 1010, 10 CYCLES-20 TO 85
SHOCK	MIL-STD-202,METHOD 213,TEST CONDITION C
VIBRATION	MIL-STD-202,METHOD 204,TEST CONDITION A
RESISTANCE TO SOLDERING HEAT	MIL-STD-202,METHOD 210,TEST CONDITION B
HUMIDITY	85% RELATIVE HUMIDITY AT 85 250 HOURS
MECHANICAL	
GROSS LEAK TEST	MIL-STD-883,METHOD 1014,TEST CONDITION C
FINE LEAK TEST	MIL-STD-883,METHOD 1014,TEST CONDITION A
TERMINAL STRENGTH	MIL-STD-202,METHOD 211,TEST CONDITION A AND C
MARKING INK	EPOXY,HEAT CURED.
MOISTURE RESISTANCE	MIL-STD-202,METHOD 106,OMIT STEP 7B
SOLDERABILITY	MIL-STD-202,METHOD 208,95% COVERAGE
SOLVENT RESISTANCE	MIL-STD-202,METHOD 2002,METHOD 215

